



**ABRACON CORPORATION  
ENGINEERING/PROCESS CHANGE NOTIFICATION FORM**

ABRACON ENGINEERING ORIGINATOR: \_\_\_\_\_

IMPLEMENTATION DATE: 10/04/2011

NOTIFICATION DATE:

10/04/2011

SCD/DRAWING AFFECTED: **AISM-1210H - High Current SMD Molded Wound Chip Inductor**

REV: **C**

NEW REV: N/A

EFFECTIVITY DATE: 10/04/2011

ECO# **M553**

**REASON FOR CHANGE:**

**Discontinuation of the AISM-1210H Series due to low demand and increased material costs**

**DETAILS OF SPECIFICATION CHANGE:**

**APPLICATION INFORMATION**

**AISM-1210H Series High Current SMD Molded Wound Chip Inductor**

Last Buy Date: **12/01/2011**

**Recommended Replacement:**

**AISC-1210H UNSHIELDED LOW PROFILE SMD POWER INDUCTOR**

**NOTE: See Datasheet for Electrical Specification; Outline Dimensions and Land Pattern**

<b>Safety</b>	<b>Non Safety</b>	<b>Application:</b>
<i>(Check one)</i>	<b>X</b>	

**DISPOSITION OF CURRENT STOCK**

- Scrap
- Transfer to: \_\_\_\_\_
- Use as is**
- Return to vendor

**ABRACON INTERNAL APPROVAL:**

SALES APPROVAL (PRES) \_\_\_\_\_ DATE 10/04/2011

PRODUCT MGR APPROVAL \_\_\_\_\_ DATE 10/04/2011

ENGINEERING MANAGER: \_\_\_\_\_ DATE 10/04/2011

PURCHASING MANAGER: \_\_\_\_\_ DATE 10/04/2011

QUALITY ASSURANCE MANAGER: \_\_\_\_\_ DATE 10/04/2011

**CUSTOMER NOTIFICATION**

ENGINEERING: NAME: \_\_\_\_\_ TITLE: \_\_\_\_\_ DATE: \_\_\_\_\_

BUYER/PURCHASING: NAME: \_\_\_\_\_ TITLE: \_\_\_\_\_ DATE: \_\_\_\_\_